



ALLIANCE MEMORY MDS REPORT

Part Number:		AS5F32G04SNDA-08LIN AS5F34G04SNDA-08LIN							
Part Weight:		78.1mg							
No.	Part Name	Material Name	Component wt (mg)	Material Content (Element)	CAS Number	Element wt (%)	Element wt (mg)	wt % of Total unit wt	PPM
1	Substrate	HL-832NX-A / AUS 308	25.141	PSR4000AUS308 Barium Sulfate	7727-43-7	7.20%	1.810	2.31772	72000
				PSR4000AUS308 Dipropylene glycolmonomethyl ether	34590-94-8	3.84%	0.965	1.23612	38400
				PSR4000AUS308 Talc containing noasbestiform fibers	14807-96-6	0.64%	0.161	0.20602	6400
				PSR4000AUS308 Epoxy resin	Trade seacret	3.52%	0.885	1.13311	35200
				PSR4000AUS308 Morpholine derivative	Trade seacret	0.64%	0.161	0.20602	6400
				PSR4000AUS308 Naphthalene	91-20-3	0.16%	0.040	0.05150	1600
				CCL-HL832NXA Cured thermosettingresin (includinginorganic filler)	Trade seacret	25.05%	6.298	8.06372	250500
				CCL-HL832NXA Continuous FilamentFiber Glass	Trade seacret	16.70%	4.199	5.37582	167000
				Cu Foil	7440-50-8	8.00%	2.011	2.57524	80000
				Au Plating	7440-57-5	0.16%	0.040	0.05150	1600
				Ni Plating	7440-02-0	1.21%	0.304	0.38951	12100
Cu Plating	7440-50-8	32.88%	8.266	10.58424	328800				
2	Mold compound	G760	37.468	2,2'-((3,3',5,5'-tetramethyl-(1,1'-biphenyl)-4,4'-diyl)bis(oxymethylene))-bis-oxirane	85954-11-6	8.00%	2.997	3.83796	80000
				Phenol Resin A	Trade Secret	2.70%	1.012	1.29531	27000
				Phenol Resin B	Trade Secret	2.80%	1.049	1.34329	28000
				Silica(Amorphous) A	60676-86-0	70.00%	26.228	33.58218	700000
				Silica(Amorphous) B	7631-86-9	8.00%	2.997	3.83796	80000
				Metal Hydroxide	Trade Secret	8.00%	2.997	3.83796	80000
3	Film	EM760	0.999	Carbon Black	1333-86-4	0.50%	0.187	0.23987	5000
				Acrylic resin (Die attach film)	Trade Secret	50.00%	0.500	0.63974	500000
				Silica, amorphous(Die attach film)	7631-86-9	45.00%	0.450	0.57577	450000
4	Solder paste	Ag	0.018	Phenol resin (Die attach film)	Trade Secret	5.00%	0.050	0.06397	50000
				Tin	7440-31-5	85.00%	0.015	0.01981	850000
				Silver	7440-22-4	2.70%	0.000	0.00063	27000
				Copper	7440-50-8	0.30%	0.000	0.00007	3000
				Solvent	Trade seacret	5.00%	0.001	0.00117	50000
				Organic amine	Trade seacret	5.00%	0.001	0.00117	50000
				polymer	Trade seacret	1.00%	0.000	0.00023	10000
				Organic acid	Trade seacret	1.00%	0.000	0.00023	10000
5	Gold wire	Au	0.141	Gold	7440-57-5	100.00%	0.141	0.17999	999960
				Calcium	7440-70-2	0.00%	0.000	0.00001	40
6	Die	Chip	14.003	Silicon	7440-21-3	98.00%	13.723	17.57102	980000
				Aluminum	7429-90-5	2.00%	0.280	0.35859	20000
7	Capacitor	0201/0.1uF	0.33	Ceramic element Barium oxide, obtained by calcining witherite	1304-28-5	40.00%	0.132	0.16901	400000
				Ceramic element Titanium dioxide	13463-67-7	20.00%	0.066	0.08451	200000
				Ceramic element Misc	Trade seacret	6.67%	0.022	0.02817	66666.66667
				Outer electrode Copper	7440-50-8	11.52%	0.038	0.04866	115151.5152
				Outer electrode diboron trioxide; boric oxide	1303-86-2	2.30%	0.008	0.00973	23030.30303
				Outer electrode Silicon dioxide	7631-86-9	9.21%	0.030	0.03892	92121.21212
				Nickel Plating Layer Nickel	7440-02-0	2.12%	0.007	0.00896	21212.12121
				Inner electrode Nickel	7440-02-0	2.42%	0.008	0.01024	24242.42424
Tin Plating Layer Tin	7440-31-5	5.76%	0.019	0.02433	57575.75758				
78.1				700.00%					
				78.100					
				100.00000					
				7000000					